

In the Claims:

Please cancel claims 32 and 35-47. Please amend claims 14 and 48-50. The claims are as follows.

1-13. (Canceled)

14. (Currently amended) An integrated chip package comprising:

a first substrate and a second substrate;

a mask on a surface of at least one of the first and second substrates, wherein the mask includes a plurality of non-circular openings, said openings having an oblong shape, an oval shape, or an elliptical shape; wherein the openings have a first dimension and a second dimension, wherein the first dimension is greater than the second dimension, and wherein the first dimension of the openings is selectively oriented on the substrate in a direction of highest stress within each interconnection; and

— a plurality of interconnections between the first and second substrates

a first substrate;

a second substrate having a plurality of circular conductive pads formed thereon with a mask covering the second substrate and portions of said pads with a plurality of interconnections formed between the first substrate and the pads formed on the second substrate,

said mask having a plurality of non-circular openings having an oblong shape, an oval shape, or an elliptical shape.

wherein the openings have a first dimension and second dimension in a plane parallel to a top surface of the second substrate, and

wherein the first dimension is greater than the second dimension and is larger than a diameter of the pads and the second dimension is smaller than the diameter, with the first dimension selectively oriented on the pad, in a direction of highest stress within each interconnection.

15-26. (Canceled)

27. (Previously presented) The integrated chip package of claim 14, wherein the openings have the oblong shape.

28. (Previously presented) The integrated chip package of claim 14, wherein the openings have the oval shape.

29. (Previously presented) The integrated chip package of claim 14, wherein the openings have the elliptical shape.

30. (Previously presented) The integrated chip package of claim 14, further comprising a plurality of traces mounted between the openings of the mask.

31. (Previously presented) The integrated chip package of claim 14, wherein the mask comprises a non-wettable material.

32. (Cancelled)

33. (Previously presented) The integrated chip package of claim 14, wherein the mask comprises an epoxy.

34. (Previously presented) The integrated chip package of claim 14, wherein the first substrate is a chip carrier, and wherein the second substrate is a printed circuit board.

35-47. (Cancelled)

48. (Currently amended) The integrated chip package of claim [[39]] 14, wherein the first substrate is a chip carrier.

49. (Currently amended) The integrated chip package of claim [[39]] 14, wherein the first substrate is a printed circuit board.

50. (Currently amended) The integrated chip package of claim [[39]] 14, further comprising interconnections formed within the openings of the mask.

51. (Previously presented) The integrated chip package of claim 50, wherein the interconnections are solder balls that wet only to an area of the conductive pads exposed by the openings in the mask.